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LEADFRAME FOR ENHANCED DOWNBOND REGISTRATION DURING AUTOMATIC WIRE BOND PROCESS

162162

ABSTRACT

A process for enhancing visual detectability of a leadframe (100) having a die attach pad (202) and a plurality of contacts (203), during automated wirebonding in the production of an integrated circuit package. At least one of a ring, a line or an array of dots are plated on the die attach pad (202) of the leadframe and around a periphery of the die attach pad. The leadframe (100) is surface treated to cause a color change on a surface of the leadframe for improved visual detectability of the at least one of the ring, the line or the dots.

Fig. 2A